



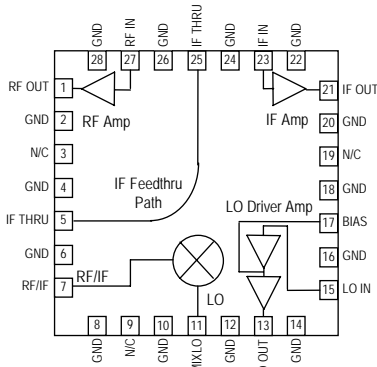
CV110-2A

Cellular-band High Linearity Downconverter

The Communications Edge™

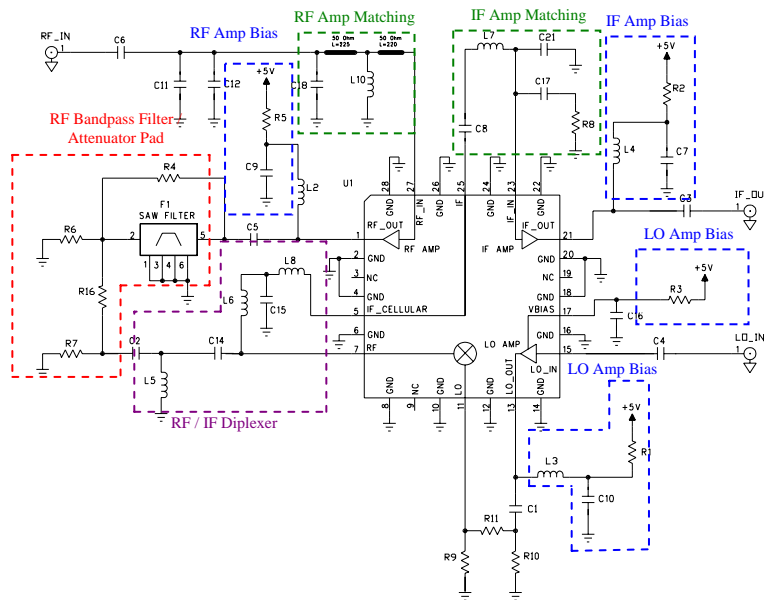
Product Information

Device Architecture / Application Circuit Information

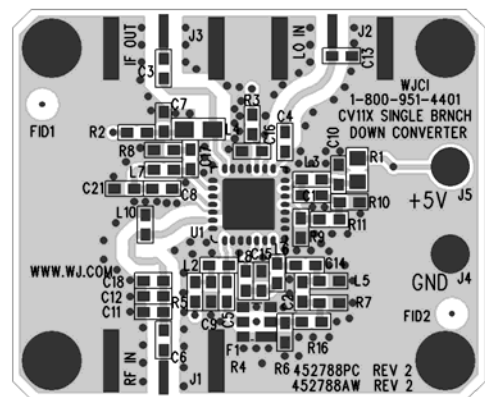


Typical Downconverter Performance Chain Analysis

Stage	Gain (dB)	Output P1dB (dBm)	Output IP3 (dBm)	NF (dB)	Current (mA)	Cumulative Performance				
						Gain (dB)	Output P1dB (dBm)	Output IP3 (dBm)	NF (dB)	
RF Amplifier	13.5	21	40.0	3.5	150	13.5	21.0	40.0	3.5	
RF Filter	-1.5	---	---	1.5	---	12.0	19.5	38.5	3.5	
MMIC Mixer	-9.0	8	23.0	9.8	60	3.0	6.1	22.1	4.5	
IF Amplifier	19.0	22	39.1	2.5	150	22.0	20.3	37.0	5.0	
CV110-2A	Cumulative Performance					360	22.0	20.3	37.0	5.0



Printed Circuit Board Material:
.014" FR-4, 4 layers, .062" total thickness



CV110-2A: The application circuit can be broken up into four main functions as denoted in the colored dotted areas above: RF/IF diplexing (purple), amplifier matching (green), filtering (red), and dc biasing (blue). There are various placeholders for chip components in the circuit schematic so that a common PCB can be used for all WJ single-branch converters. Additional placeholders for other optional functions such as filtering are also included.

RF / IF Amplifier Matching: The RF amplifier requires a shunt matching element for optimal gain and input return loss performance. The IF amplifier requires matching elements to optimize the performance of the amplifier to the desired IF center frequency. Since IF bandwidths are typically on the order of 5 to 10%, a simple two element matching network, in the form of either a high-pass or low-pass filter structure, is sufficient to match the MMIC IF amplifier over these narrow bandwidths. Proper component values for other IF center frequencies can be provided by emailing to applications.engineering@wj.com.

RF Bandpass Filtering: Bandpass filtering is recommended to reject the image frequencies and achieve the best noise figure

performance with the downconverter. The bandpass filter, implemented with a SAW filter on the application circuit, allows for the suppression of noise from the image frequency. It is permissible to not use a filter and use a 2 dB pad with R6, R7, and R16 instead with slightly degraded noise figure performance. Standard WJ evaluation boards will have the 2 dB pad in place.

External Diplexer: In a downconversion application, the incoming RF signal impinges on the switching elements of the mixer; the interaction with these switches produces a signal at the IF frequency. The two signals (RF and IF) are directed to the appropriate ports by the external diplexer. Pin 5 contains the IF signal and allows the signal to be transferred to pin 25 for the convenience of PCB layouts.

DC biasing: DC bias must be provided for the RF, LO and IF amplifiers in the converter. R1 sets the operating current for the last stage of the LO amplifier and is chosen to optimize the mixer LO drive level. Proper RF chokes and bypass capacitors are chosen for proper amplifier biasing at the intended frequency of operation. The "+5 V" dc bias should be supplied directly from a voltage regulator.



CV110-2A

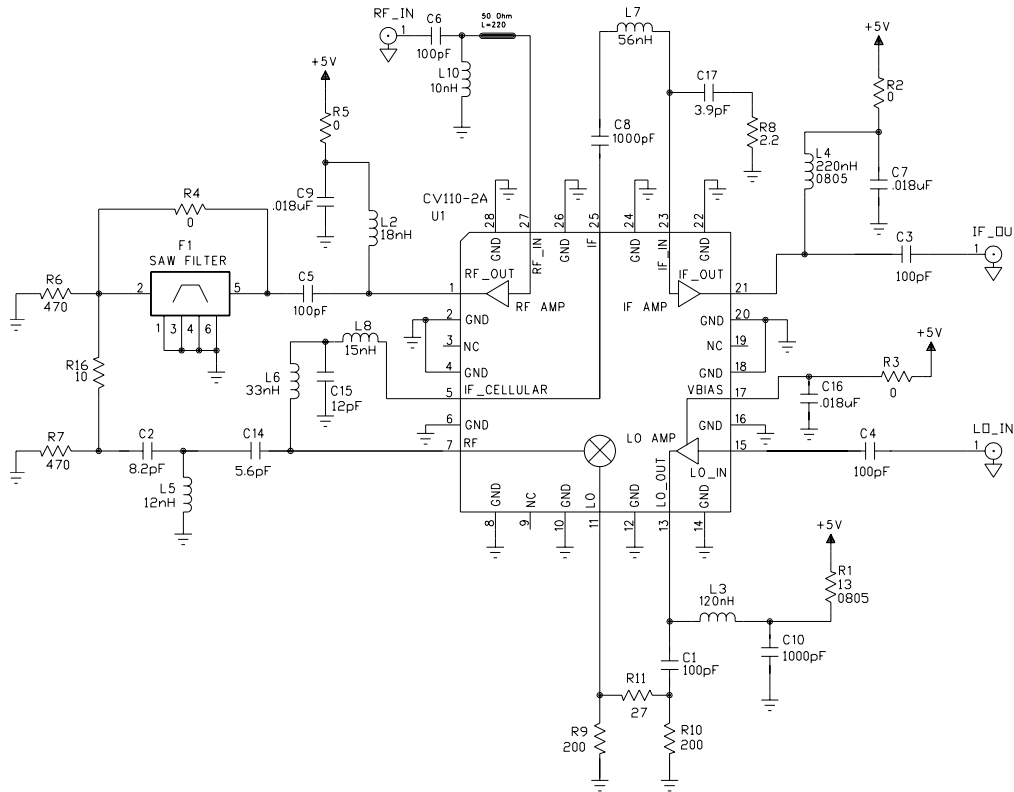
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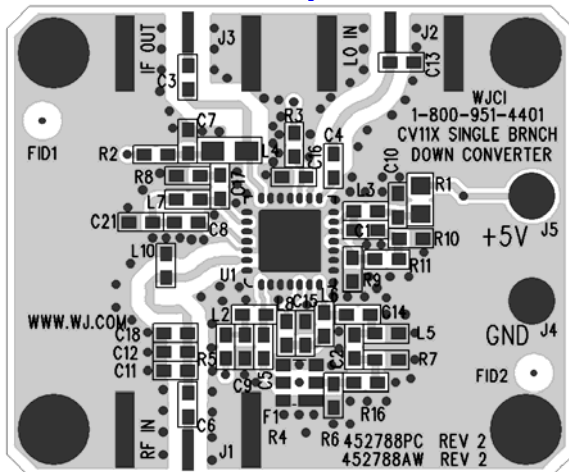
Product Information

Downconverting Application Circuit: CV110-2APCB240

RF = 800 – 960 MHz, IF = 240 MHz



PCB Layout



Circuit Board Material: .014" FR-4, 4 layers, .062" total thickness

Bill of Materials

Ref. Desig.	Component
R1	13 Ω chip resistor, size 0805
R2, R3, R4, R5	0 Ω chip resistor
R6, R7	470 Ω chip resistor
R8	2.2 Ω chip resistor
R9, R10	200 Ω chip resistor
R11	27 Ω chip resistor
R16	10 Ω chip resistor
C1, C3, C4, C5, C6	100 pF chip capacitor
C2	8.2 pF chip capacitor
C7, C9, C16	0.018 μF chip capacitor
C8, C10	1000 pF chip capacitor
C11, C12, C13, C18, C21, F1	Shown in silkscreen, but not used in actual circuit.
C14	5.6 pF chip capacitor
C15	12 pF chip capacitor
C17	3.9 pF chip capacitor
C18	1.5 pF chip capacitor
L2	18 nH chip inductor
L3	120 nH chip inductor
L4	220 nH chip inductor, size 0805
L5	12 nH chip inductor
L6	33 nH chip inductor
L7	56 nH chip inductor
L8	15 nH chip inductor
L10	10 nH chip inductor
U1	CV110-2A WJ Converter

All components are of size 0603 unless otherwise specified.

Specifications and information are subject to change without notice



CV110-2A

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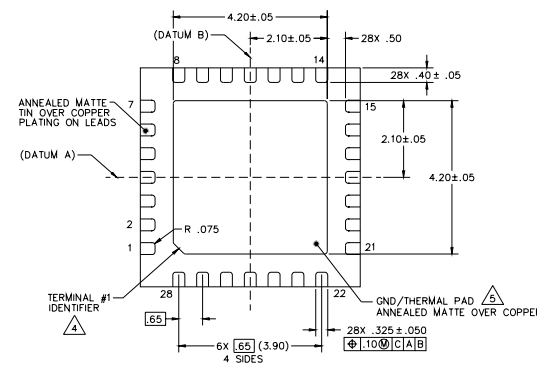
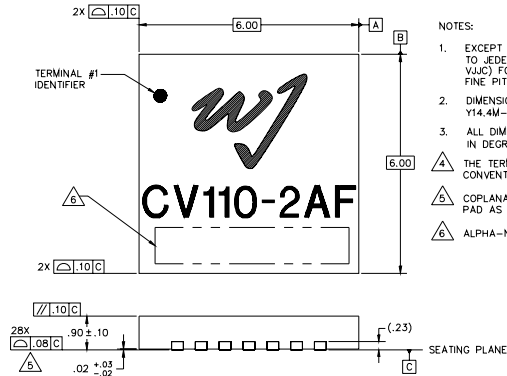
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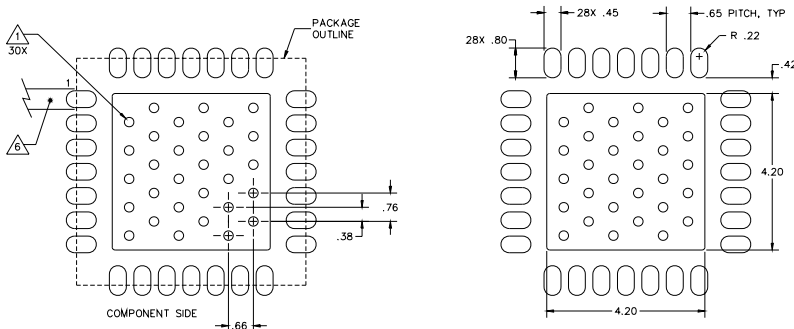
CV110-2AF Mechanical Information

This package is lead-free/RoHS-compliant. It is compatible with both lead-free (maximum 260°C reflow temperature) and leaded (maximum 245°C reflow temperature) soldering processes. The plating material on the pins is annealed matte tin over copper.

Outline Drawing



Mounting Configuration / Land Pattern



- NOTES:
- GROUND/THERMAL VIAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. VIAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL PLATED THRU DIAMETER OF .25mm (.010").
 - ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
 - TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
 - ADD MOUNTING SCREWS NEAR THE PART TO FASTEN THE BOARD TO A HEATSINK. ENSURE THAT THE GROUND/THERMAL VIA REGION CONTACTS THE HEATSINK.
 - DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.
 - RF TRACE WIDTH DEPENDS UPON THE PC BOARD MATERIAL AND CONSTRUCTION.
 - USE 1 OZ. COPPER MINIMUM.
 - ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

Product Marking

The component will be lasermarked with a "CV110-2AF" product label with an alphanumeric lot code on the top surface of the package.

Tape and reel specifications for this part will be located on the website in the "Application Notes" section.

ESD / MSL Information



Caution! ESD sensitive device.

ESD Rating: Class 1B
 Value: Passes $\geq 500V$ to $<1000V$
 Test: Human Body Model (HBM)
 Standard: JEDEC Standard JESD22-A114

ESD Rating: Class III
 Value: Passes $\geq 500V$ to $<1000V$
 Test: Charged Device Model (CDM)
 Standard: JEDEC Standard JESD22-C101

MSL Rating: Level 2 at +260°C convection reflow
 Standard: JEDEC Standard J-STD-020

Functional Pin Layout

Pin	FUNCTION	Pin	FUNCTION
1	RF Amp Output	15	LO Amp Input
2	GND	16	GND
3	N/C	17	LO Amp Bias
4	GND	18	GND
5	IF Feedthru Port	19	N/C or GND
6	GND	20	GND
7	Mixer RF / IF Port	21	IF Amp Output/Bias
8	GND	22	GND
9	N/C or GND	23	IF Amp Input
10	GND	24	GND
11	Mixer LO Input	25	IF Feedthru Port
12	GND	26	GND
13	LO Amp Output	27	RF Amp Input
14	GND	28	GND

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